







(COFP) 0.50 MM LEAD PITCH WITH CERAMIC NON-CONDUCTIVE TIE BAR OUTLINES 6

COMMON DIMENSIONS DIMENSIONS ARE IN MILLIMETERS

SYMBQL	MIN.	NOM.	MAX.	NOTES
A	2.16	3.55	4.55	3
АІ	2.00	3.19	4.00	4
A2	0.05	0.20	0.35	
Ь	0.19	0.21	0.25	
Ь	0.18	0.20	0.22	10
С	0.11	0.16	0.20	
сІ	0.10	0.15	0.17	10
е		0.50 BASIC		
G	1.45	1.50	1.55	
J	0.75	0.90	1.05	
K			0.50	
L	74.85	75.25	76.40	6
LI	74.60	75.00	75.40	
L2	55.60	56.30	57.00	
М			0.015	
NOTES	9, 13, 14			
REF	10-317			
ISSUE	Α			

	TITLE	ISSUE	DATE		PAGE
JEDEC SOLID STATE PRODUCT OUTLINES	CERAMIC QUAD FLATPACK FAMILY (CQFP) 0.50 MM LEAD PITCH WITH CERAMIC NON- CONDUCTIVE TIE BAR	Α	May 92	MO-134	4 0F 6

SYX	VAR:	IATIO	n (al	L) DIM	MENSIC	DNS AF	RE	INI	MILLI	METER	≀S
B O	AA			ZO		AB	_	02		AC		NO Z
	MIN.	NOM.	MAX.	ΙE	MIN.	NOM.	MAX.	E	MIN.	NOM.	MAX.	TE
D1 E1	31.68	32.00	32.32		35.64	36.00	36.36		39.60	40.00	40.40	
D2 E2	27.5 BASIC				31.5 BASIC				35.5 BASIC			
F	6.85	7.75	8.65		6.85	7.75	8.65		4.5	5.0	5.5	
Ν	224					256 7				288		
ND		56		8		64		8		72		8
R	12.50		-		10.90				11.60			
Y	19.20 BASIC 17.20 BASIC 15.20 BASIC											
NOTES	ES 9, 13, 14											
REF	10-	-317										
ISSUE		Α										

S Y M	VAR	IATIO	N (AL	L) DIM	MENSIC	DNS AF	RE	IN MILLIMETERS
B 0		AD		NO		AE		Z O	
L	MIN.	NOM.	MAX.	T E	MIN.	NOM.	MAX.	T E	
DI	43.56	44.00	44.44		47.52	48.00	48.48		
D2 E2	39.5 BASIC				4	3.5 BASI	С		
F	4.5	5.0	5.5		4.5	5.0	5.5		
Z	320			7		352		7	
ND		80		8		88		8	
R	10.00				7.95				
Y	-	3.20 BAS	IC			.20 BAS	IC		
NOTES	9, 13	, 14							
REF	10-3	17							
ISSUE	А								

	TITLE	ISSUE	DATE		PAGE
JEDEC SOLID STATE PRODUCT OUTLINES	CERAMIC QUAD FLATPACK FAMILY (CQFP) 0.50 MM LEAD PITCH WITH CERAMIC NON- CONDUCTIVE TIE BAR	А	May 92	MO-134	5 0F 6

NC	ES:
\triangle	AN INDEX MARK SHALL BE LOCATED WITHIN THE SHADED AREA SHOWN.
2	GENERIC LEAD ATTACH DOGLEG DEPICTION. FLAT LEAD CONFIGURATION IS OPTIONAL.
3	NCLUDES HEATSINK OPTION. TOTAL THICKNESS INCLUDES LEAD ATTACH DOGLEG HEIGHT OR LID HEIGHT, WHICHEVER IS GREATER.
4	INCLUDES HEATSINK OPTION.
5 7. 8. 9.	EDGE CHAMFERS ARE OPTIONAL. PIN #1 MAY HAVE OPTIONAL FEATURE (LARGE CHAMFER OR NOTCH) FOR MECHANICAL ORIENTATION PURPOSES. DIMENSION L: DIMENSION L INCLUDES MAXIMUM LEAD TIP OVERHANG DIMENSION N: NUMBER OF LEADS. DIMENSION ND: NUMBER OF LEADS PER PACKAGE EDGE. ENTERPRET DIMENSIONS AND TOLERANCES IN ACCORDANCE WITH ANSI Y14.5M. DIMENSION BI AND CI APPLY TO BASE METAL ONLY. DIMENSION M APPLIES TO
	PLATING THICKNESS.
<u> </u>	CHAMFER TIE BAR APPLIES TO 224 AND 256 LEADCOUNTS ONLY. SQUARE TIE BAR APPLIES TO 288, 320 AND 352 LEADCOUNTS ONLY.
12	EADTIP POSITION SHALL BE MEASURED IN A ZONE 5MM IN LENGTH FROM EXTERNAL EDGE OF CERAMIC TIE BAR.
13.	ALL DIMENSIONS ARE IN MILLIMETERS. TOLERANCE IS ±0.125 MM UNLESS OTHERWISE SPECIFIED.
14.	TEATURES NOT DIMENSIONED ARE PACKAGE SUPPLIER'S OPTION.
SOLI	JEDEC STATE PRODUCT (CQFP) 0.50 MM LEAD PITCH OUTLINES WITH CERAMIC NON-CONDUCTIVE TIE BAR TITLE CERAMIC QUAD FLATPACK FAMILY (CQFP) 0.50 MM LEAD PITCH A May 92 MO-134 OF 6